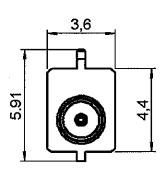
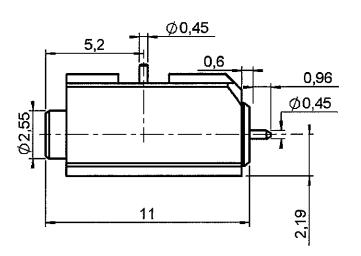
REEL OF 500

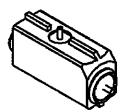
R199.005.890

Series : MC-CARD









All dimensions are in mm.



BODY CENTER CONTACT DUTER CONTACT INSULATOR GASKET OTHERS PARTS BRASS BERYLLIUM COPPER - POLYETHER ETHERCETONE 30 - STAINLESS STEEL	GOLD 0.2 OVER NICKEL 2 GOLD 0.8 OVER NICKEL 2
OTHERS PARTS STAINLESS STEEL	% GF
	-
-	

Issue: 0449 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL OF 500

R199.005.890

Series: MC-CARD

PACKAGING

Standard	Unit	Other
500	'W' option	Contact us

SPECIFICATION

* 1.4 max at 2.5 GHz. 00

ELECTRICAL CHARACTERISTICS

Impedance

50 Ω

Frequency

0-3 GHz

VSWR

1.4* + 0.000 x F(GHz) Maxi

Insertion loss RF leakage **0.3**** √F(GHz) dB Maxi - F(GHz)) dB Maxi

Voltage rating

100 Veff Maxi

Dielectric withstanding voltage Insulation resistance

250 Veff mini 5000 MΩ mini

ENVIRONMENTAL

Operating temperature

Hermetic seal

-40/+110 ° C

Panel leakage

- Atm.cm3/s

ranei leakage

OTHERS CHARACTERISTICS

Assembly instruction

NA

Others:

isol between 2 ways: -22dBmin at 2.5 GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force - Mating end

Axial force – Opposite end

Torque

- N mini

- N.cm mini

Recommended torque

Mating

- N.cm

Panel nut

- N.cm

Mating life

5000 Cycles mini

Weight

0.985 g

Issue: 0449 D

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REEL OF 500

R199.005.890

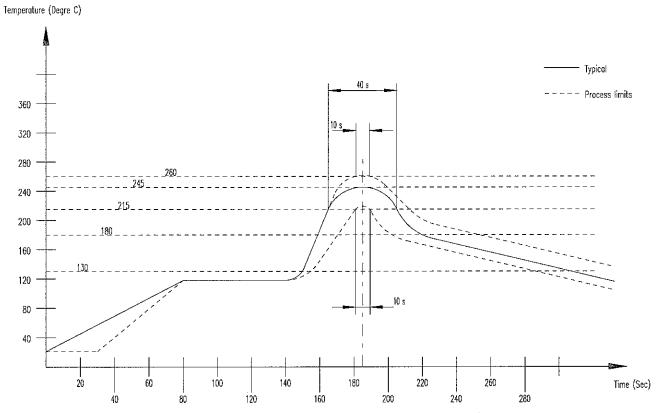
Series: MC-CARD

SOLDER PROCEDURE OF SWITCH EDGE CARD RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1. Deposit solder paste 'SN62RP11AGS90' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE: The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



Issue: 0449 D
In the effort to improve our products, we reserve the right to make changes judged to be necessary.

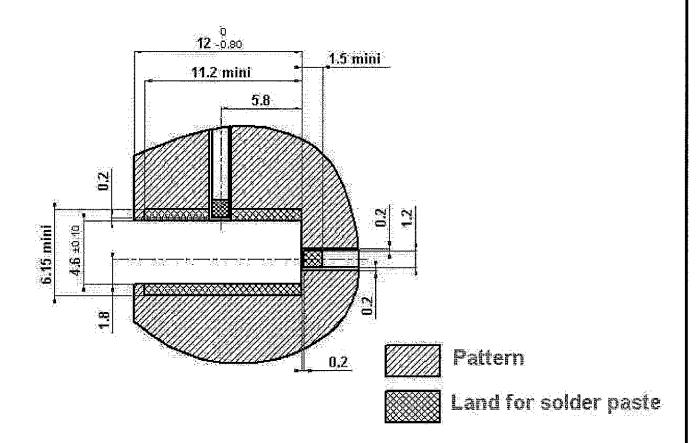


REEL OF 500

R199.005.890

Series: MC-CARD

INTORMATIONS



COPLANAR LINE:

Ground and signal are on the same side.

Thickness of PCB: 1 mm.

The material of PCB is glass – epoxy composite (Er=4.8)

The solder resist should be printed except for the land pattern of the PCB.

Issue: 0449 D

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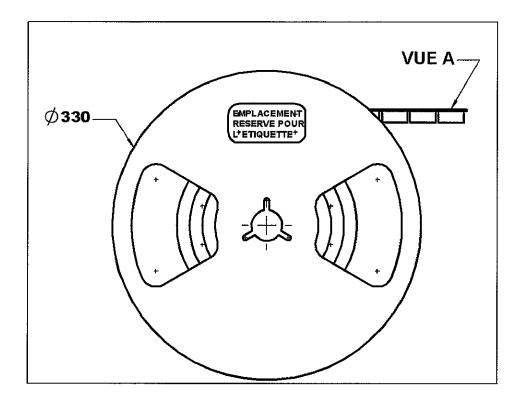


REEL OF 500

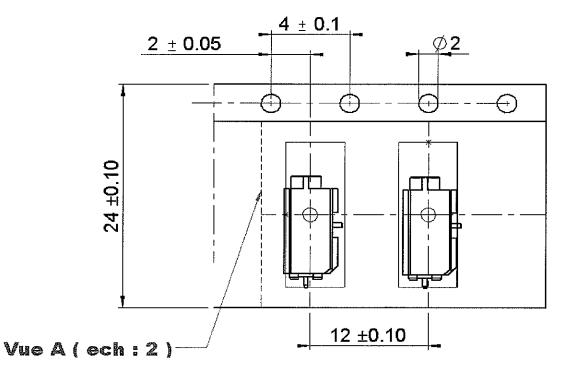
R199.005.890

Series: MC-CARD

PACKAGING



bobine Ech: 0.7



Issue: 0449 D
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